

Electronic Patent Application Fee Transmittal

Application Number:	10598514			
Filing Date:	29-Jan-2007			
Title of Invention:	Multiple stacked die window csp package and method of manufacture			
First Named Inventor/Applicant Name:	Chuen Khiang Wang			
Filer:	Linda Johnson Hodge/Ramon Linsangan			
Attorney Docket Number:	P26634			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 2 months with \$0 paid	1252	1	490	490

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				490